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Features

Configuration

DGD2184M

600V HALF BRIDGE GATE DRIVER IN SO-8

Floating High-Side Driver in Bootstrap Operation to 600V

1.4A Source / 1.8A Sink Output Current Capability

Internal Dead Time of 395ns to Protect MOSFETs Wide Low-Side Gate Driver and Logic Supply: 10V to 20V

Schmitt Triggered Logic Inputs with Internal Pull Down

Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

control (i.e. parts gualified to AEC-Q100/101/104/200, PPAP

capable, and manufactured in IATF 16949 certified

Halogen and Antimony Free. "Green" Device (Note 3) For automotive applications requiring specific change

Undervoltage Lockout for High and Low Side Drivers

Extended Temperature Range: -40°C to +125°C

Outputs Tolerant to Negative Transients

Logic Input (IN and SD*) 3.3V Capability

Drives Two N-Channel MOSFETs or IGBTs in Half Bridge

Description

The DIODES™ DGD2184M is a high voltage / high speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD2184M's high-side to switch to 600V in a bootstrap operation.

The DGD2184M logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. The DGD2184M has a fixed internal deadtime of 395ns (typ).

The DGD2184M is offered in SO-8 (Type TH) package, the operating temperature extends from -40°C to +125°C.

Applications

- **DC-DC** converters
- **DC-AC** inverters
- AC-DC power supplies
- Motor controls
- Class D power amplifiers



Typical Configuration

Ordering Information (Note 4)

| Part Number | Paakaga | Marking | Reel Size (inch) | Tape Width (mm) | Pa | cking |
|---------------|----------------|----------|------------------|-----------------|-------|---------|
| | Package | warking | Reel Size (Inch) | rape width (mm) | Qty. | Carrier |
| DGD2184MS8-13 | SO-8 (Type TH) | DGD2184M | 13 | 12 | 2,500 | Reel |

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

Notes:





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facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Package: SO-8
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.075 grams (Approximate)

SO-8 (Type TH)



Top View



Pin Diagrams



Top View SO-8 (Type TH)

Pin Descriptions

| Pin Number | Pin Name | Function |
|------------|----------|--|
| 1 | IN | Logic Input for High-Side and Low-Side Gate Driver Outputs (HO and LO), in Phase with HO |
| 2 | SD* | Logic Input for Shutdown, Enabled Low |
| 3 | COM | Low-Side and Logic Return |
| 4 | LO | Low-Side Gate Drive Output |
| 5 | Vcc | Low-Side and Logic Fixed Supply |
| 6 | Vs | High-Side Floating Supply Return |
| 7 | НО | High-Side Gate Drive Output |
| 8 | VB | High-Side Floating Supply |

Functional Block Diagram





Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--|-----------------|---|------|
| High-Side Floating Supply Voltage | VB | -0.3 to +624 | V |
| High-Side Floating Supply Offset Voltage | Vs | V _B – 24 to V _B + 0.3 | V |
| High-Side Floating Output Voltage | Vно | Vs – 0.3 to V _B + 0.3 | V |
| Offset Supply Voltage Transient | dVs/dt | 50 | V/ns |
| Low-Side Fixed Supply Voltage | V _{CC} | -0.3 to +24 | V |
| Low-Side Output Voltage | VLO | -0.3 to Vcc + 0.3 | V |
| Logic Input Voltage (IN and SD*) | VIN | -0.3 to V _{CC} + 0.3 | V |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|---|--------|-------------|------|
| Power Dissipation Linear Derating Factor (Note 5) | PD | 0.625 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Reja | 200 | °C/W |
| Operating Temperature | TJ | +150 | |
| Lead Temperature (Soldering, 10s) | TL | +300 | °C |
| Storage Temperature Range | Tstg | -55 to +150 |] |

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

| Parameter | Symbol | Min | Max | Unit |
|--|-----------------|----------|---------|------|
| High-Side Floating Supply Absolute Voltage | VB | Vs + 10 | Vs + 20 | V |
| High-Side Floating Supply Offset Voltage | Vs | (Note 6) | 600 | V |
| High-Side Floating Output Voltage | V _{HO} | Vs | VB | V |
| Low-Side Fixed Supply Voltage | Vcc | 10 | 20 | V |
| Low-Side Output Voltage | VLO | 0 | Vcc | V |
| Logic Input Voltage (IN and SD*) | Vin | 0 | Vcc | V |
| Ambient Temperature | TA | -40 | +125 | С |

Note: 6. Logic operation for V_S of -5V to +600V.



DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Notes 7, 8)

| _ | | | _ | | | |
|---|--------------------|-----|-----|-----|------|--------------------------------|
| Parameter | Symbol | Min | Тур | Max | Unit | Conditions |
| Logic "1" Input Voltage | VIH | 2.5 | | | V | $V_{CC} = 10V$ to 20V |
| Logic "0" Input Voltage | VIL | — | _ | 0.8 | V | Vcc = 10V to 20V |
| SD* Input Positive Going Threshold | V _{SDTH+} | 2.5 | — | | V | $V_{CC} = 10V$ to 20V |
| SD* Input Negative Going Threshold | VSDTH- | — | _ | 0.8 | V | Vcc = 10V to 20V |
| High Level Output Voltage, VBIAS – Vo | Vон | — | _ | 1.2 | V | $I_0 = 0 m A$ |
| Low Level Output Voltage, V _O | Vol | — | _ | 0.1 | V | $I_0 = 20 \text{mA}$ |
| Offset Supply Leakage Current | Ilκ | — | — | 50 | μA | $V_B = V_S = 600V$ |
| Quiescent VBS Supply Current | IBSQ | 20 | 60 | 150 | μA | $V_{IN} = 0V \text{ or } 5V$ |
| Quiescent Vcc Supply Current | lccq | 0.4 | 1.0 | 1.8 | mA | $V_{IN} = 0V \text{ or } 5V$ |
| Logic "1" Input Bias Current | lin+ | — | 25 | 60 | μA | IN = 5V, SD* = 0V |
| Logic "0" Input Bias Current | I _{IN-} | — | — | 1.0 | μA | IN = 0V, SD* = 5V |
| VBS Supply Under-Voltage Positive Going Threshold | VBSUV+ | 8.0 | 8.9 | 9.8 | V | — |
| V _{BS} Supply Under-Voltage Negative Going Threshold | V _{BSUV-} | 7.4 | 8.2 | 9.0 | V | — |
| V _{CC} Supply Under-Voltage Positive Going Threshold | V _{CCUV+} | 8.0 | 8.9 | 9.8 | V | — |
| Vcc Supply Under-Voltage Negative Going Threshold | Vccuv- | 7.4 | 8.2 | 9.0 | V | — |
| Output High Short Circuit Pulsed Current | I _{O+} | 1.4 | 1.9 | _ | Α | V _O = 0V, PW ≤ 10µs |
| Output Low Short Circuit Pulsed Current | lo- | 1.7 | 2.3 | | А | Vo = 15V, PW ≤ 10µs |

7. The V_{IN} and I_{IN} parameters are applicable to the two logic input pins: IN and SD*. The V_O and I_O parameters are applicable to the respective output Notes: pins: HO and LO. 8. For optimal operation, it is recommended that the input pulses (IN and SD*) should have a minimum amplitude of 2.5V with a minimum pulse width of

800ns.

AC Electrical Characteristics (VBIAS (VCC, VBS) = 15V, CL = 1000pF, @TA = +25°C, unless otherwise specified.)

| Parameter | Symbol | Min | Тур | Max | Unit | Conditions |
|----------------------------------|-------------------|-----|-----|-----|------|------------------|
| Turn-On Propagation Delay | ton | — | 680 | 900 | ns | $V_{\rm S} = 0V$ |
| Turn-Off Propagation Delay | toff | — | 270 | 400 | ns | Vs = 0V or 600V |
| Shut-Down Propagation Delay | tsp | — | 180 | 270 | ns | — |
| Delay Matching, HO & LO Turn-On | t _{DMON} | — | — | 90 | ns | — |
| Delay Matching, HO & LO Turn-Off | t DMOFF | — | _ | 40 | ns | $I_{O} = 0A$ |
| Turn-On Rise Time | tR | — | 40 | 60 | ns | $V_S = 0V$ |
| Turn-Off Fall Time | tF | — | 20 | 35 | ns | Vs = 0V |
| Deadtime: tdt lo-ho & tdt ho-lo | tот | 345 | 395 | 445 | ns | — |



Timing Waveforms







Figure 2. Shutdown Waveform Definitions



 $\begin{array}{l} \text{Deadtime } t_{\text{DT }\text{LO-HO}} = t_{\text{ON }\text{HO}} + t_{\text{OFF }\text{LO}} \\ t_{\text{DT }\text{HO-LO}} = t_{\text{ON }\text{LO}} - t_{\text{OFF }\text{HO}} \\ \text{Deadtime matching} \\ t_{\text{MDT}} = t_{\text{DT }\text{LO-HO}} - t_{\text{DT }\text{HO-LO}} \end{array}$

Delay matching tDM OFF = tOFF LO - tOFFT HO

Figure 3. Switching Time Waveform Definitions



Typical Performance Characteristics (@T_A = +25°C, V_{CC} = 15V, unless otherwise specified.)





Figure 4. Turn-on Propagation Delay vs. Supply Voltage



Figure 6. Turn-off Propagation Delay vs. Supply Voltage



Figure 8. Rise Time vs. Supply Voltage

Figure 5. Turn-on Propagation Delay vs. Temperature



Figure 7. Turn-off Propagation Delay vs. Temperature



Figure 9. Rise Time vs. Temperature













Figure 18. Output Sink Current vs. Supply Voltage



Figure 20. Logic 1 Input Voltage vs. Supply Voltage







Figure 19. Output Sink Current vs. Temperature



Figure 21. Logic 1 Input Voltage vs. Temperature













-40 -20 0 20 40 60 80 100 120 Temperature (°C)

Figure 27. VBS UVLO vs. Temperature

0





Figure 28. Offset Supply Leakage Current vs. Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8 (Type TH)

SO-8 (Type TH)

| 9 | SO-8 (Type TH) | | | | | |
|-------|----------------------|-------|------|--|--|--|
| Dim | Min | Max | Тур | | | |
| Α | 1.35 | 1.75 | | | | |
| A1 | 0.10 | 0.25 | | | | |
| A2 | | | 1.45 | | | |
| b | 0.35 | 0.51 | | | | |
| c | 0.190 | 0.248 | | | | |
| D | 4.80 | 5.00 | 4.90 | | | |
| Е | 5.80 | 6.20 | 6.00 | | | |
| E1 | 3.80 | 4.00 | 3.90 | | | |
| e | - | | 1.27 | | | |
| h | 0.25 | 0.50 | | | | |
| L | 0.41 | 1.27 | | | | |
| L1 | - | | 1.04 | | | |
| Ø | 0° | 8° | | | | |
| All [| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 1.27 |
| C1 | 5.20 |
| Х | 0.60 |
| Y | 2.20 |

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